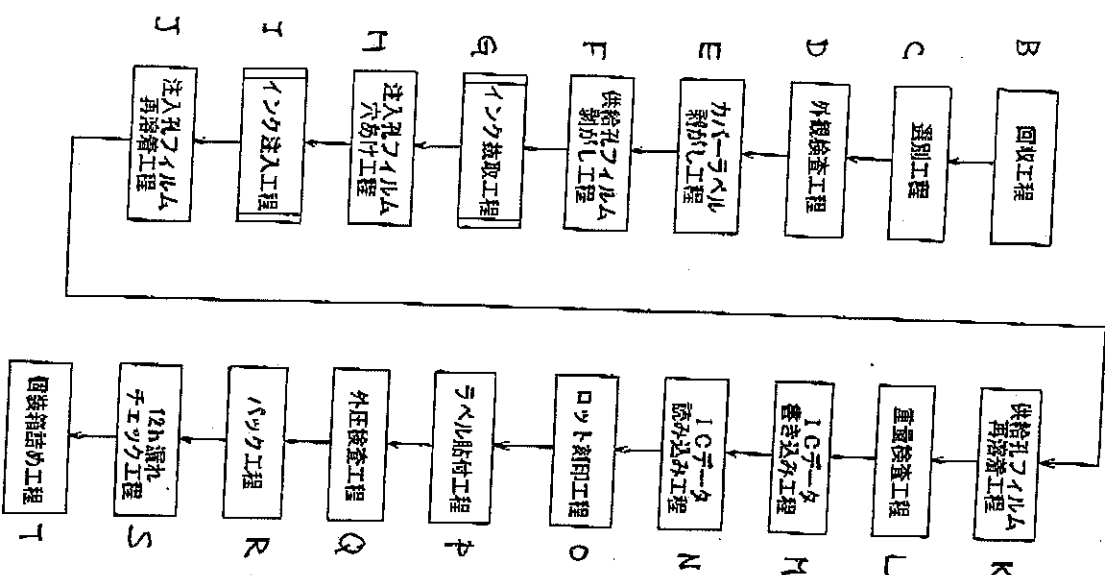


Fig. 1

A リサイクル工程

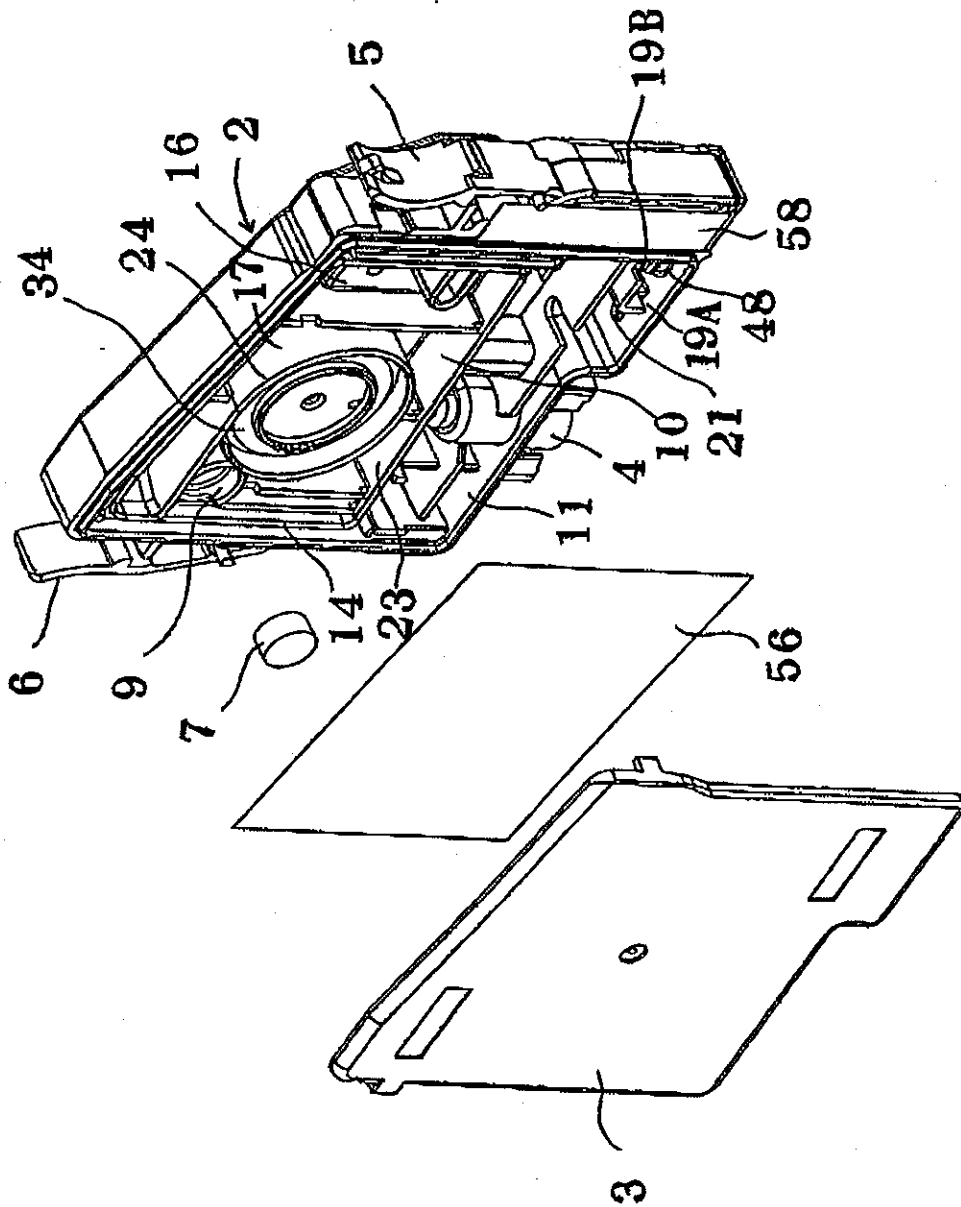


[FIG. 1]

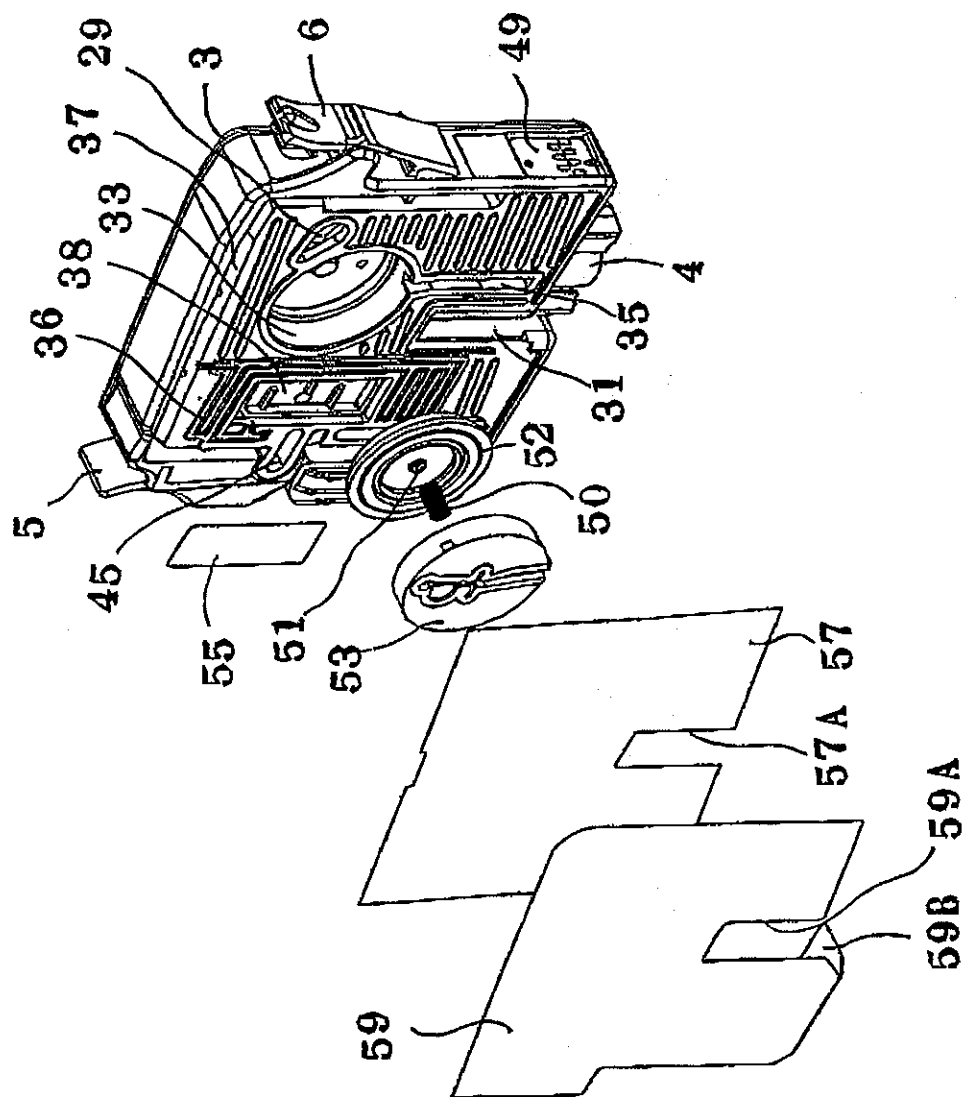
- A: RECYCLING PROCESS
- B: RECOVERING PROCESS
- C: SORTING PROCESS
- D: APPEARANCE INSPECTING PROCESS
- E: COVER LABEL PEELING PROCESS
- F: SUPPLYING OPENING FILM PEELING PROCESS
- G: INK EXTRACTING PROCESS
- H: INJECTION HOLE FILM PIERCING PROCESS
- I: INK INJECTING PROCESS
- J: INJECTION HOLE FILM REMELDING PROCESS
- K: SUPPLYING HOLE FILM REMELDING PROCESS
- L: WEIGHT INSPECTING PROCESS
- M: IC DATA WRITING PROCESS
- N: IC DATA READING PROCESS
- O: LOT IMPRINTING PROCESS
- P: LABEL ADHERING PROCESS
- Q: EXTERNAL PRESSURE INSPECTING PROCESS
- R: PACKING PROCESS
- S: 12H LEAKAGE CHECKING PROCESS
- T: INDIVIDUAL ENCASING PROCESS

【図2】

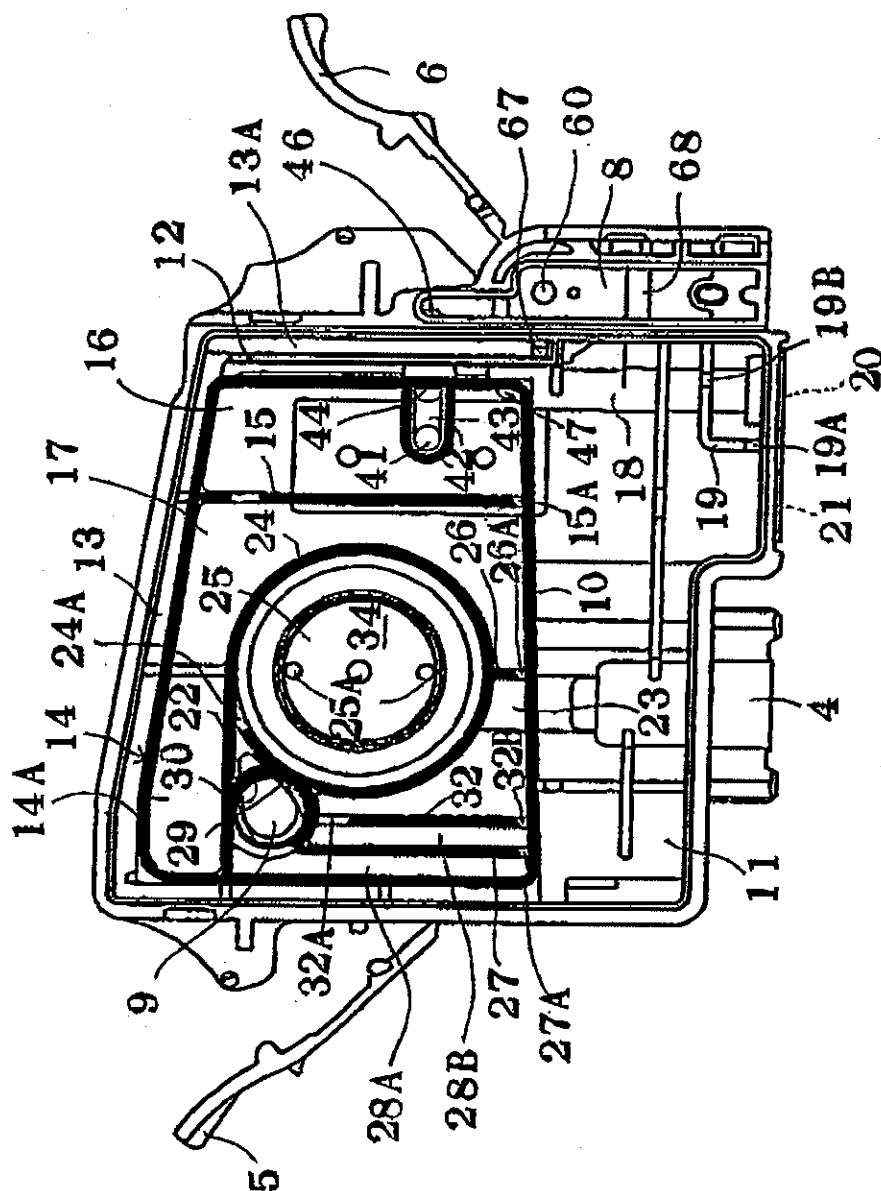
Fig. 2



【図3】 Fig. 3



【図4】 Fig. 4



【図5】 Fig. 5

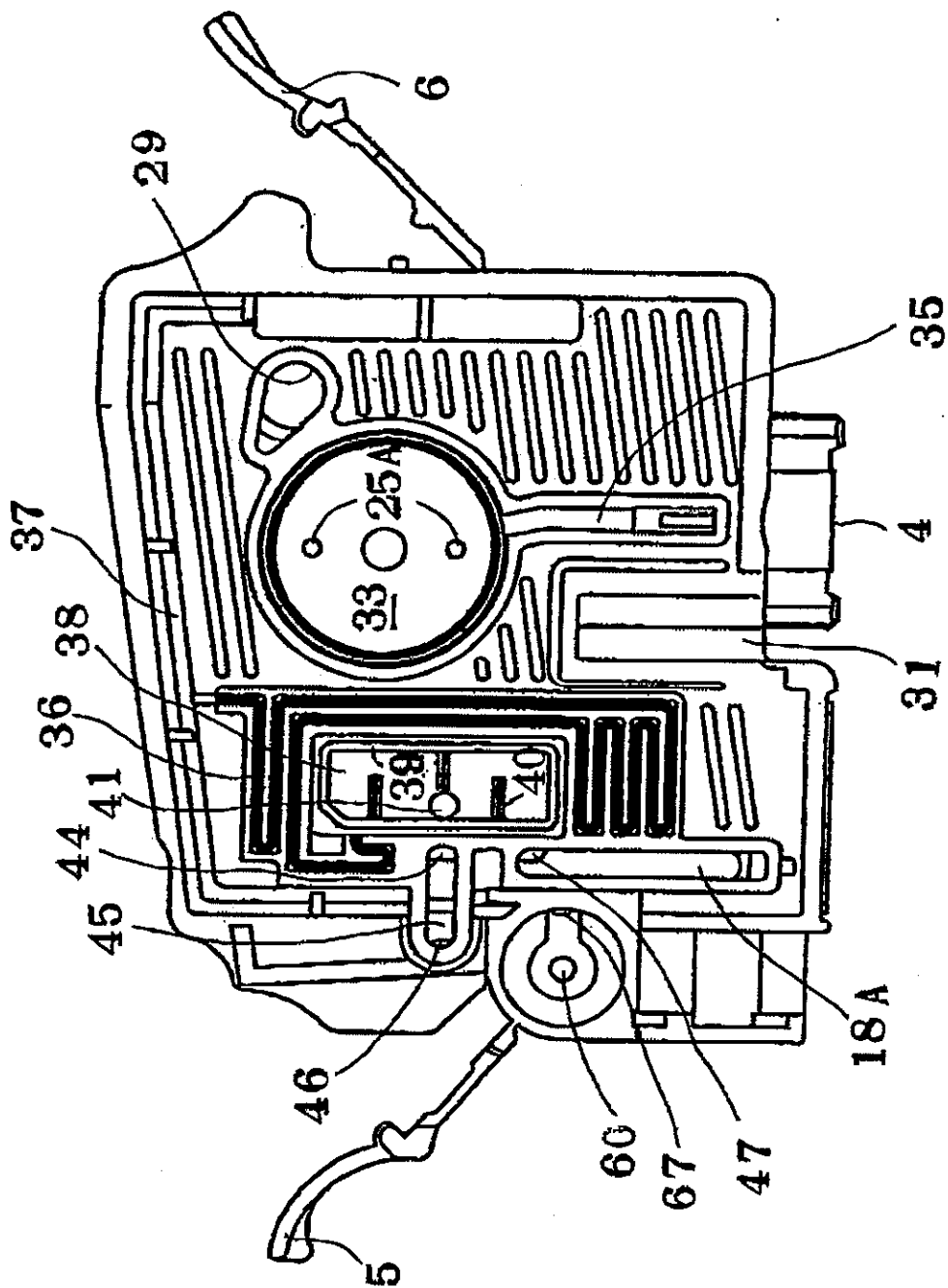
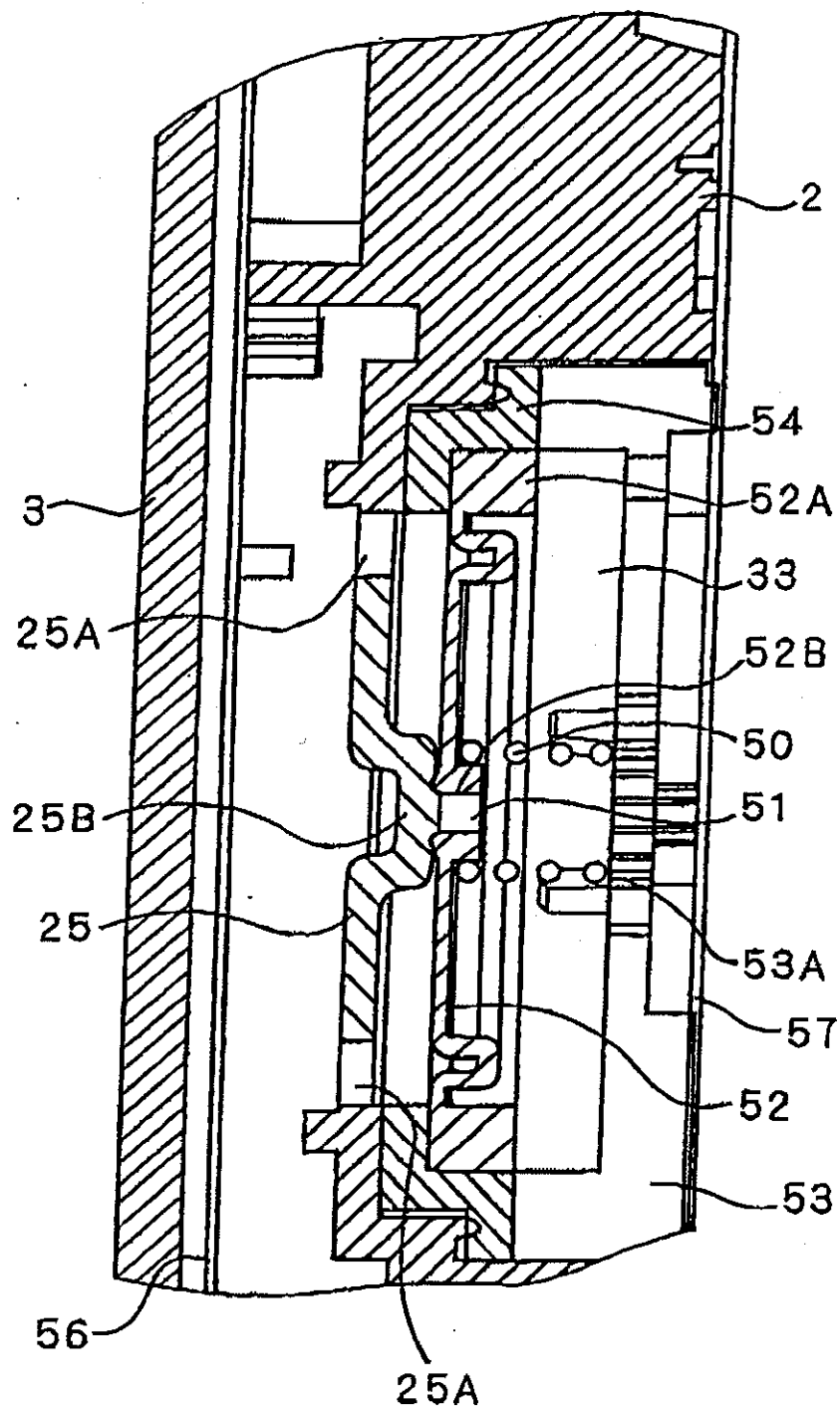
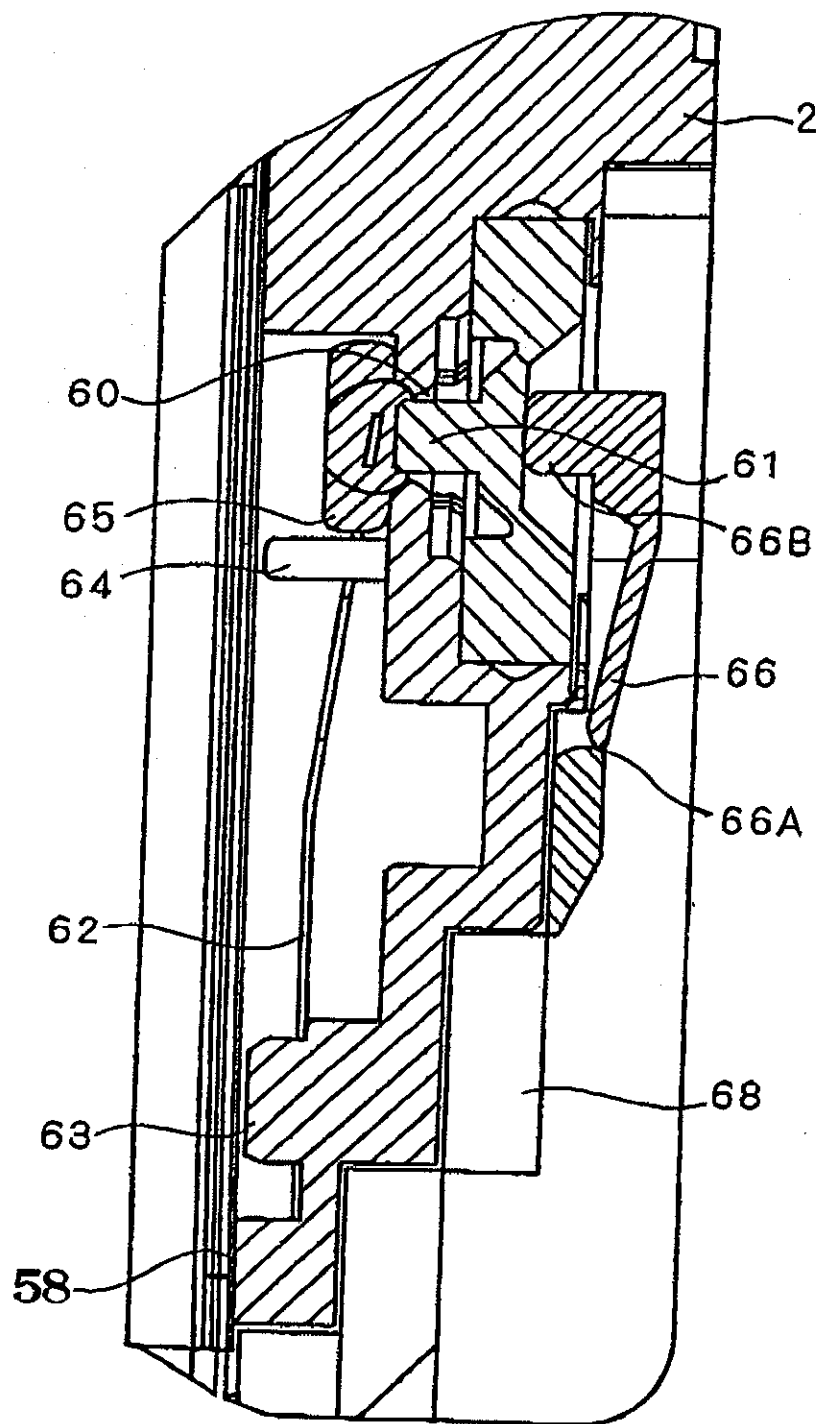


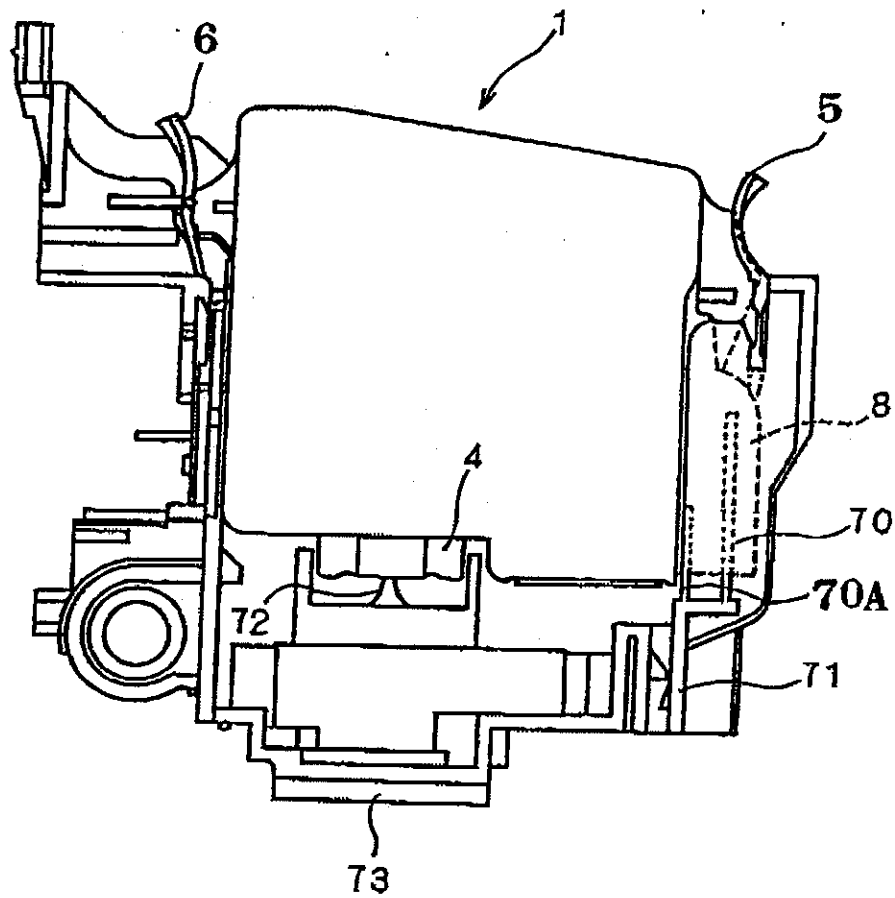
図6 Fig. 6



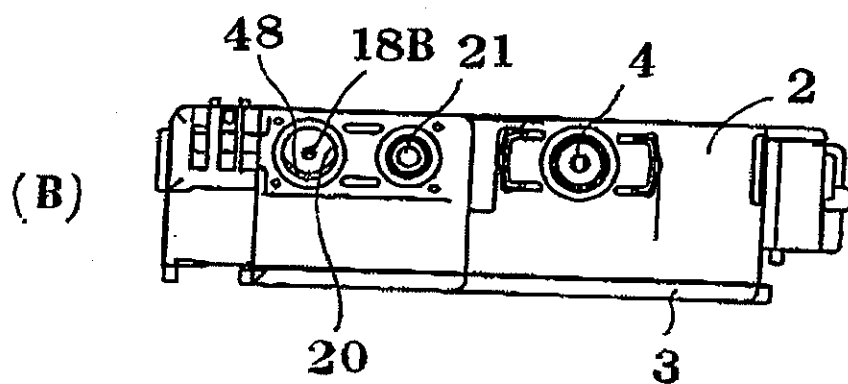
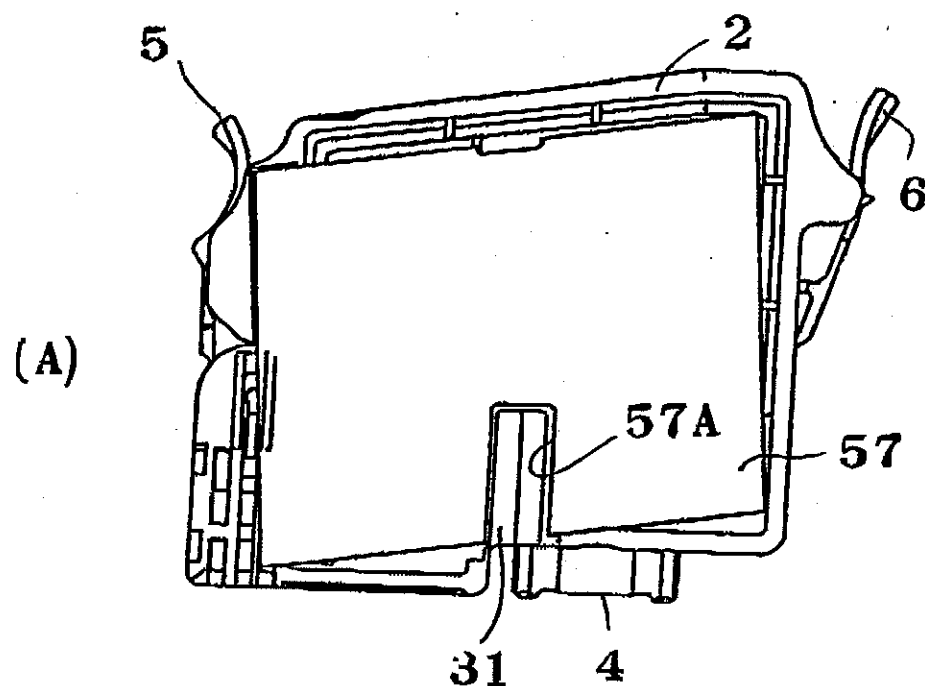
【図7】 Fig. 7



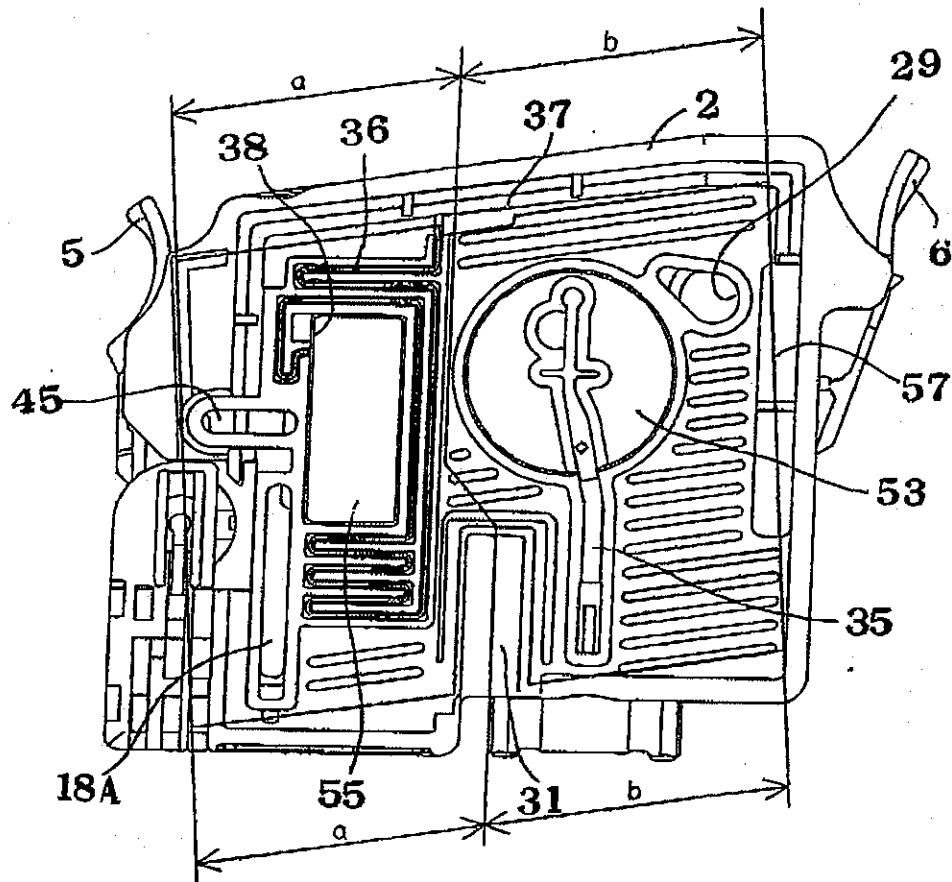
【図8】 Fig. 8



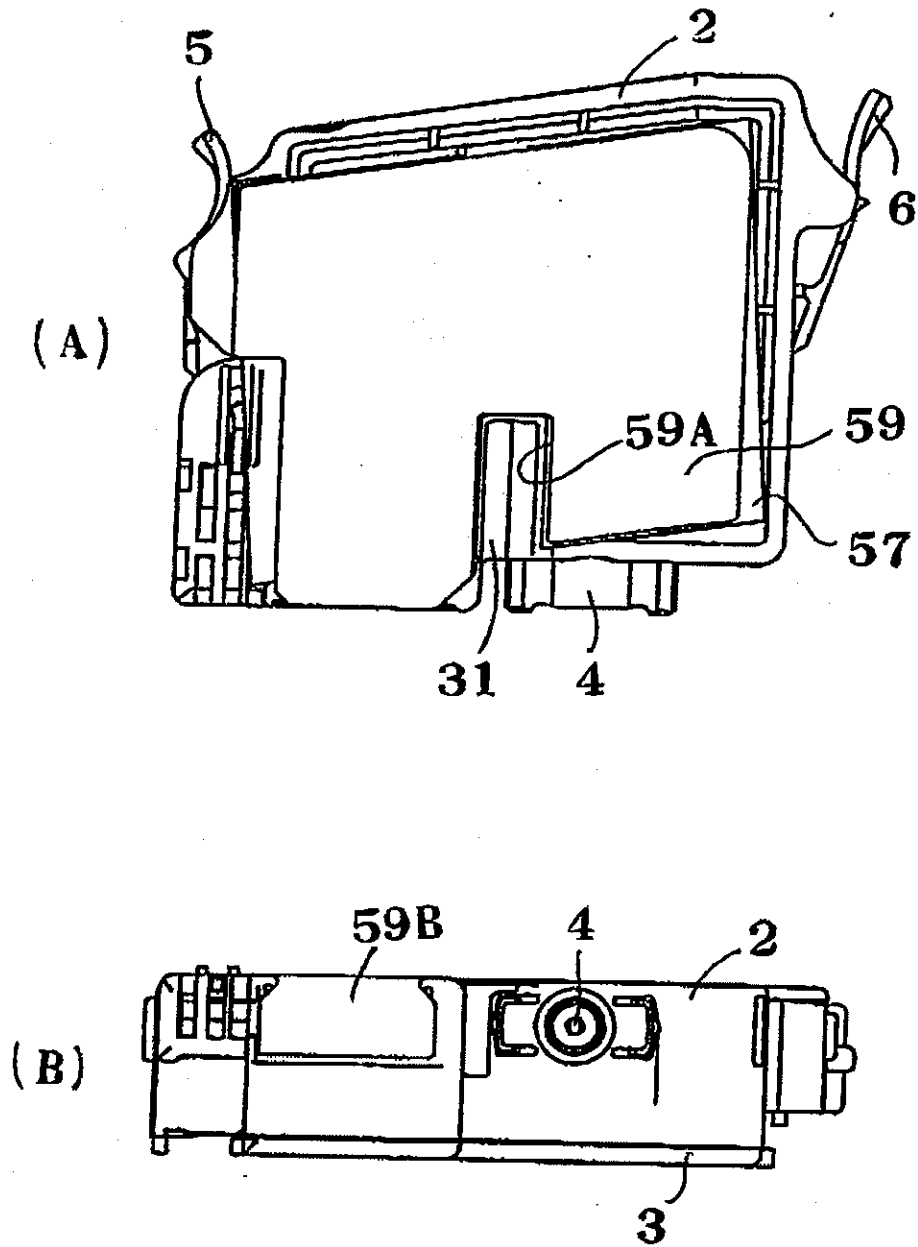
【図9】 Fig. 9



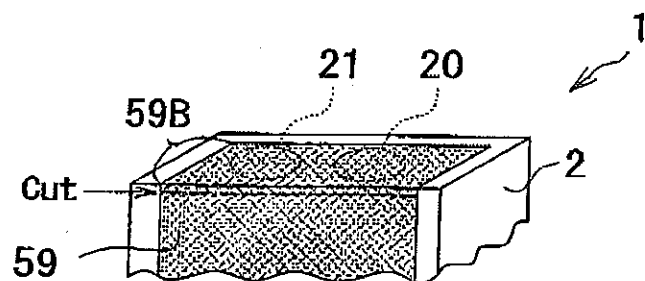
【図10】 Fig. 10



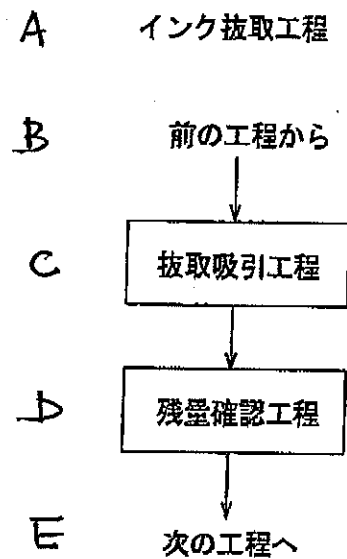
【図11】 Fig. 11



【図12】 Fig. 12



【図13】 Fig. 13

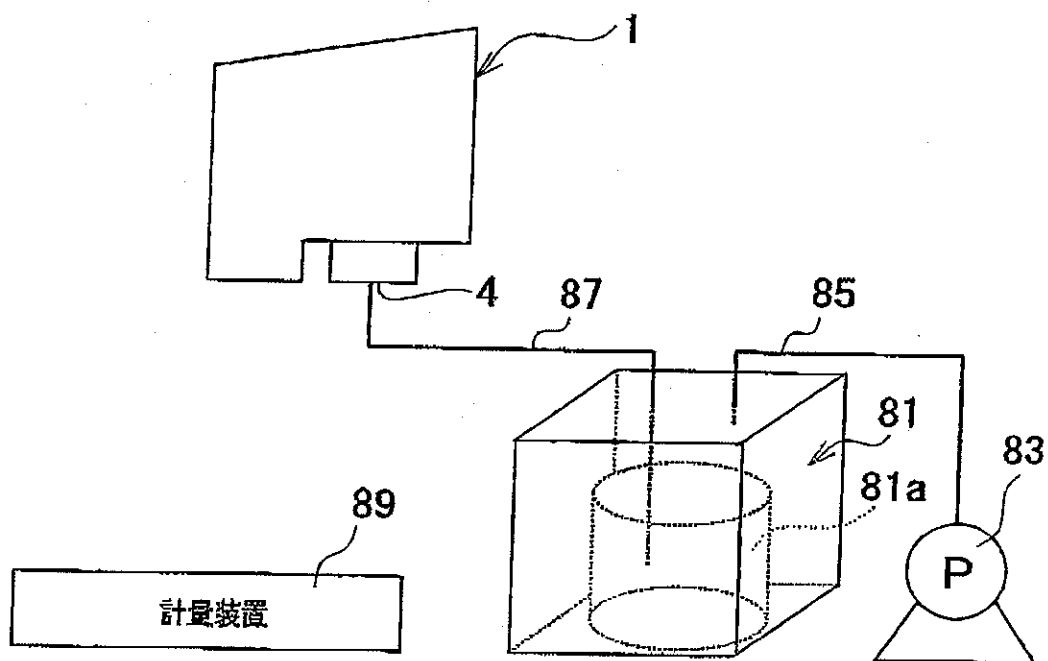


[FIG. 13]

- A: INK EXTRACTING PROCESS
- B: FROM THE PREVIOUS PROCESS
- C: EXTRACTING AND SUCKING PROCESS
- D: REMAINING AMOUNT CHECKING PROCESS
- E: TO THE NEXT PROCESS

【図14】 Fig. 14

A インク採取工程



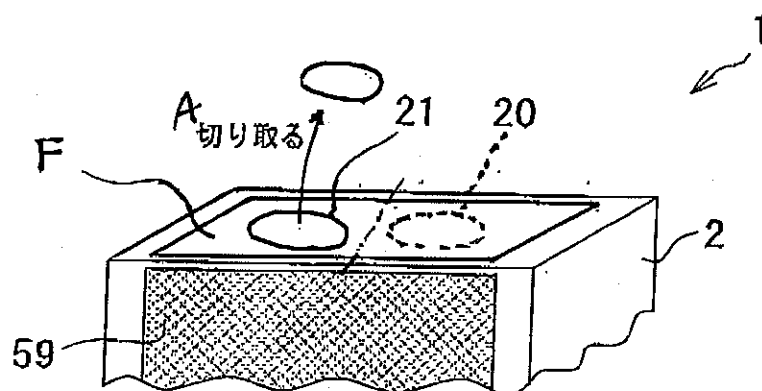
[FIG. 14]

A: INK EXTRACTING PROCESS

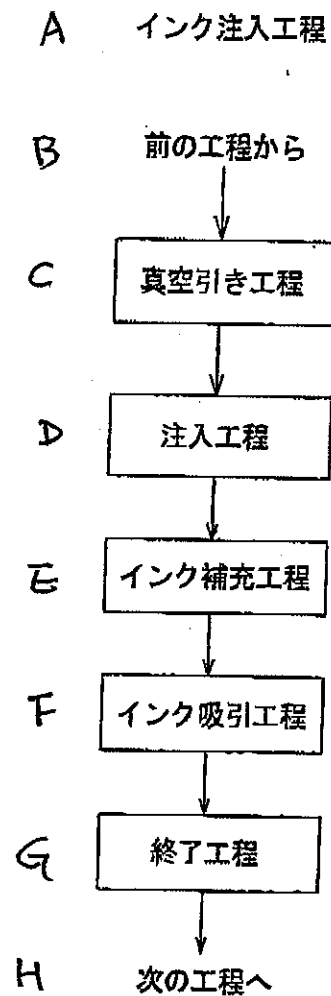
89: MEASURING DEVICE

【図15】 Fig. 15

A: CUT OUT

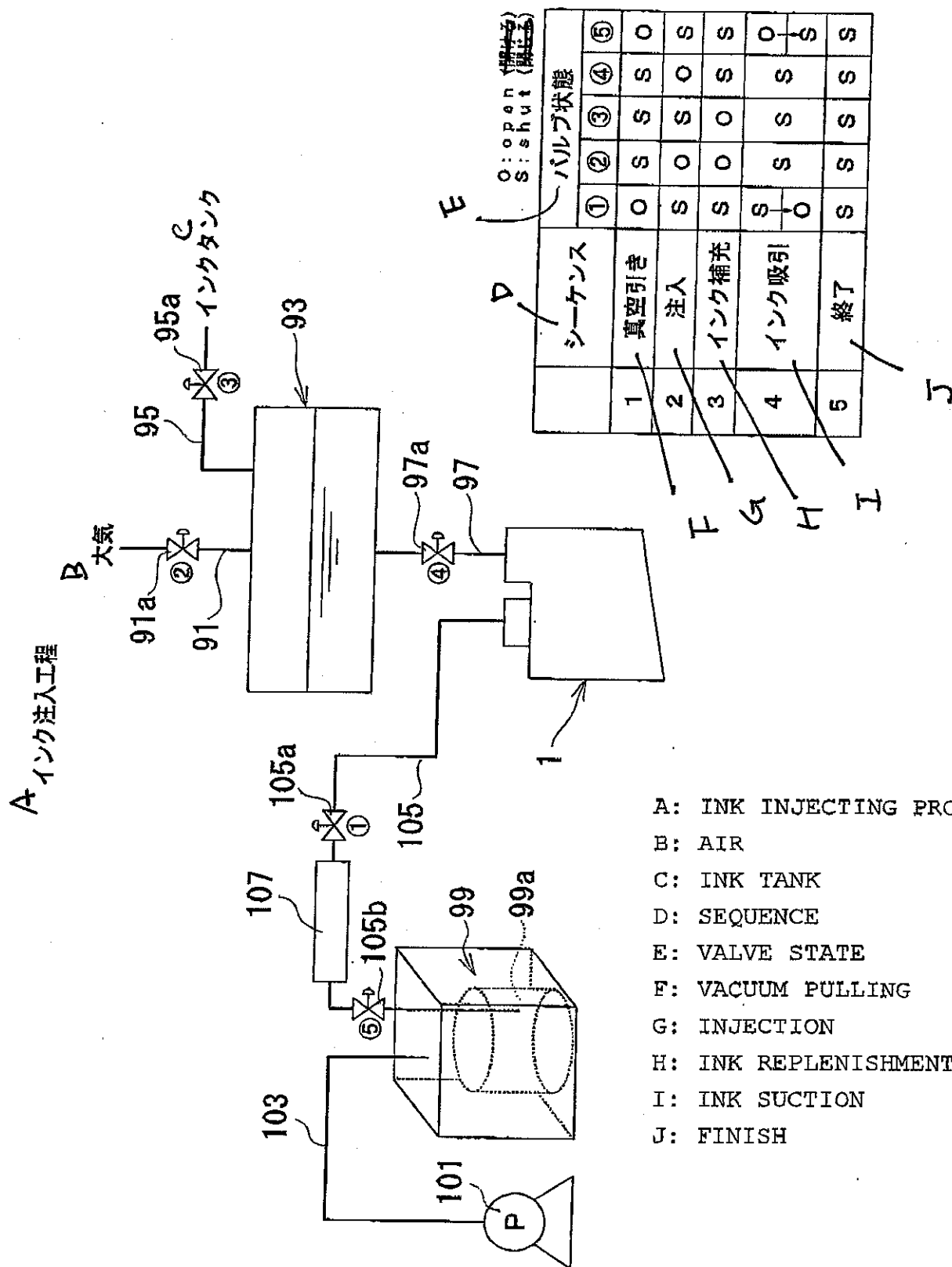


【図16】 Fig. 16



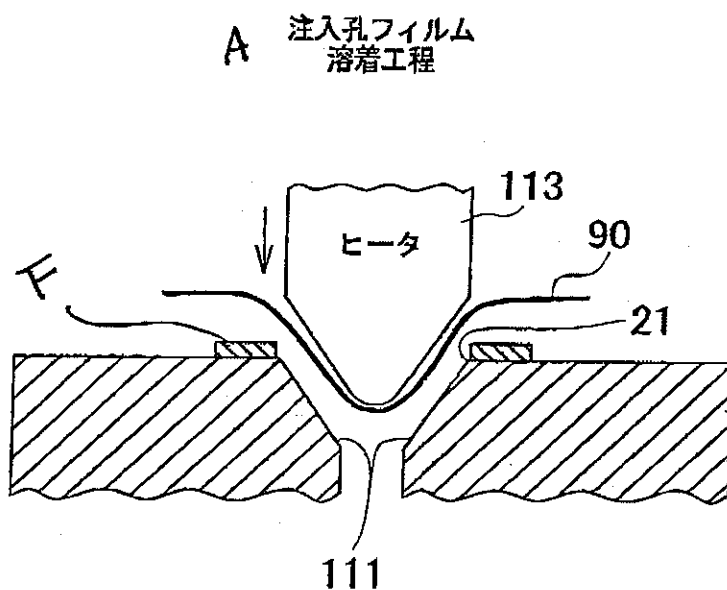
- A: INK INJECTING PROCESS
- B: FROM THE PREVIOUS PROCESS
- C: VACUUM PULLING PROCESS
- D: INJECTING PROCESS
- E: INK REPLENISHING PROCESS
- F: INK SUCTION PROCESS
- G: FINISHING PROCESS
- H: TO THE NEXT PROCESS

【図17】 Fig. 17



- A: INK INJECTING PROCESS
B: AIR
C: INK TANK
D: SEQUENCE
E: VALVE STATE
F: VACUUM PULLING
G: INJECTION
H: INK REPLENISHMENT
I: INK SUCTION
J: FINISH

【図18】 Fig. 18.



A: INJECTION HOLE FILM WELDING PROCESS
113: HEATER

Fig. 19
(a)

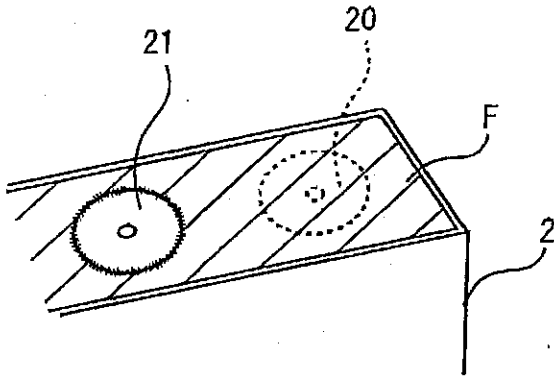
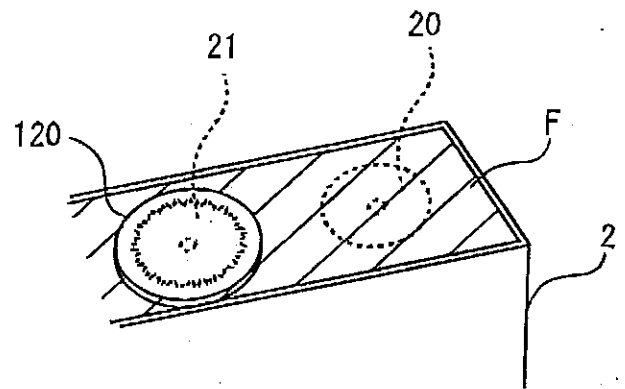


Fig. 19
(b)



【図20】

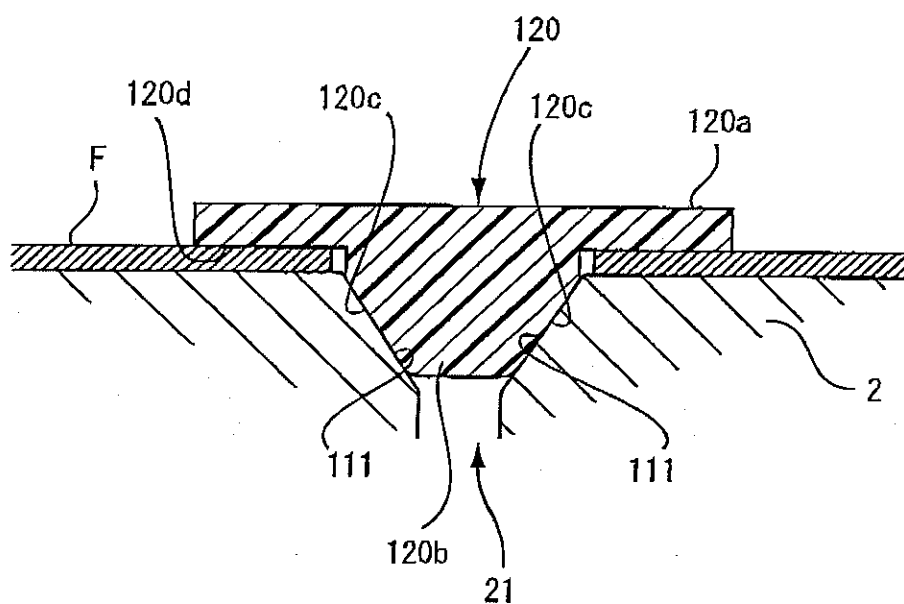


Fig. 20